

# Tohru Suwa

## List of Publications by Year in descending order

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22  
papers

187  
citations

1163117

8  
h-index

1125743

13  
g-index

22  
all docs

22  
docs citations

22  
times ranked

188  
citing authors

#	ARTICLE	IF	CITATIONS
1	Redesigning a commercial combined cycle in an undergraduate thermodynamics course: Connecting theory to practical cycle design. International Journal of Mechanical Engineering Education, 2020, , 030641902090464.	1.0	1
2	Solar Irradiance Fluctuation Prediction Methodology Using Artificial Neural Networks. Journal of Solar Energy Engineering, Transactions of the ASME, 2020, 142, .	1.8	5
3	Transient thermal prediction methodology for parabolic trough solar collector tube using artificial neural network. Renewable Energy, 2019, 131, 168-179.	8.9	34
4	Performance of a small-scale solar cogeneration system in the equatorial zone of Malaysia. Energy Conversion and Management, 2019, 184, 127-138.	9.2	11
5	Sky image-based solar irradiance prediction methodologies using artificial neural networks. Renewable Energy, 2019, 134, 837-845.	8.9	59
6	Interdisciplinary new product development projects extended over engineering and management courses. , 2017, , .		0
7	Thermal Modeling Technique for Multiple Transistors Within Silicon Chip. Journal of Electronic Packaging, Transactions of the ASME, 2011, 133, .	1.8	1
8	Optimal placement of heat generating components at various levels of electronics packaging. Microelectronics Journal, 2010, 41, 129-134.	2.0	3
9	Multidisciplinary Design and Optimization for Oscillating Flow Polymerase Chain Reaction Microfluidics Device. , 2009, , .		0
10	Multi-Packaging-Level Thermal Modeling Technique for Silicon Chip Transistors. , 2009, , .		0
11	Multidisciplinary heat generating logic block placement optimization using genetic algorithm. Microelectronics Journal, 2008, 39, 1200-1208.	2.0	7
12	Multidisciplinary Design and Optimization Methodologies in Electronics Packaging: State-of-the-Art Review. Journal of Electronic Packaging, Transactions of the ASME, 2008, 130, .	1.8	16
13	Multidisciplinary Placement Optimization of Heat Generating Electronic Components on Printed Circuit Boards. Journal of Electronic Packaging, Transactions of the ASME, 2007, 129, 90-97.	1.8	9
14	Multidisciplinary Placement Optimization of Heat Generating Electronic Components on a Printed Circuit Board in an Enclosure. IEEE Transactions on Components and Packaging Technologies, 2007, 30, 402-410.	1.3	13
15	Multidisciplinary Electronic Package Design and Optimization Methodology Based on Genetic Algorithm. IEEE Transactions on Advanced Packaging, 2007, 30, 402-410.	1.6	11
16	Multidisciplinary Heat Generating Logic Block Placement Optimization Using Genetic Algorithm. , 2007, , .		1
17	Multidisciplinary Heat Generating Cell Placement Optimization Using Genetic Algorithm and Artificial Neural Networks. , 2006, , .		4
18	Integrated Multidisciplinary Design and Optimization Methodologies in Electronics Packaging: State-of-the-Art Review. , 2006, , .		1

#	ARTICLE	IF	CITATIONS
19	A Multidisciplinary Design and Optimization Methodology for Ball Grid Array Packages Using Artificial Neural Networks. Journal of Electronic Packaging, Transactions of the ASME, 2005, 127, 306-313.	1.8	8
20	Multidisciplinary Placement Optimization of Heat Generating Electronic Components on Printed Circuit Boards Using Artificial Neural Networks. , 2005, , 2079.		1
21	Multidisciplinary Placement Optimization of Heat Generating Electronic Components on Printed Circuit Board in Channel Flow Forced Convection Using Artificial Neural Networks. , 2005, , .		0
22	Integrated Thermomechanical Design and Optimization of BGA Packages Using Genetic Algorithm. , 2004, , 495.		2